M1MA151WAT1, M1MA152WAT1

Preferred Device

Common Anode Silicon Dual Switching Diodes

These Common Anode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC–59 package which is designed for low power surface mount applications.

Features

- Fast t_{rr}, < 10 ns
- Low C_D, < 15 pF
- Pb–Free Packages are Available

MAXIMUM RATINGS (T_A = 25°C)

Rating		Symbol	Value	Unit
Reverse Voltage M1MA151WAT1 M1MA152WAT1		V_R	 40 80	Vdc
Peak Reverse Voltage M1MA151WAT1 M1MA152WAT1		V_{RM}	 40 80	Vdc
Forward Current	Single Dual	I_F	100 150	mAdc
Peak Forward Current	Single Dual	I_{FM}	225 340	mAdc
Peak Forward Surge Current	Single Dual	I_{FSM} (Note 1)	500 750	mAdc

THERMAL CHARACTERISTICS

| Rating	Symbol	Max	Unit
Power Dissipation	P_D	200	mW
Junction Temperature	T_J	150	°C
Storage Temperature	T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
1. t = 1 SEC

3 ANODE
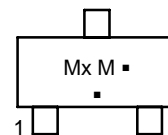
2 CATHODE 1

SC–59
CASE 318D

1
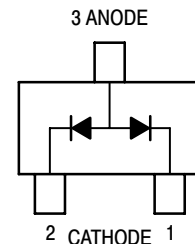
MARKING DIAGRAM

Mx M ▪

1

Mx = Device Code
    x = N for 151
        O for 152
M = Date Code*
▪ = Pb–Free Package
(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping[†]
M1MA151WAT1	SC–59	3000/Tape & Reel
M1MA151WAT1G	SC–59 (Pb–Free)	3000/Tape & Reel
M1MA152WAT1	SC–59	3000/Tape & Reel
M1MA152WAT1G	SC–59 (Pb–Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

M1MA151WAT1, M1MA152WAT1

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current M1MA151WAT1 M1MA152WAT1	I_R	V_R = 35 V V_R = 75 V	–	0.1	μAdc
Forward Voltage	V_F	I_F = 100 mA	–	1.2	Vdc
Reverse Breakdown Voltage M1MA151WAT1 M1MA152WAT1	V_R	I_R = 100 μA	40 80	–	Vdc
Diode Capacitance	C_D	V_R = 0, f = 1.0 MHz	–	15	pF
Reverse Recovery Time (Figure 1)	t_{rr} (Note 2)	I_F = 10 mA, V_R = 6.0 V, R_L = 100 Ω, I_{rr} = 0.1 I_R	–	10	ns

2. t_{rr} Test Circuit

RECOVERY TIME EQUIVALENT TEST CIRCUIT
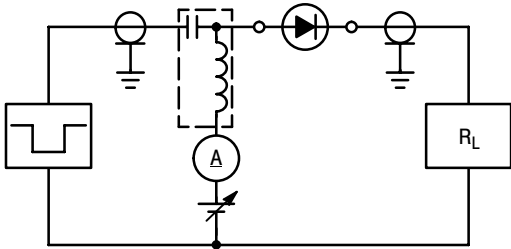
INPUT PULSE

OUTPUT PULSE

t_p = 2 μs
t_r = 0.35 ns

I_{rr} = 0.1 I_R
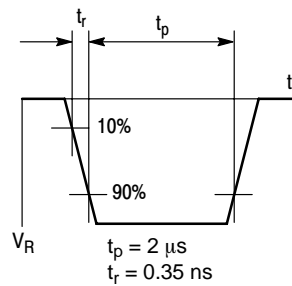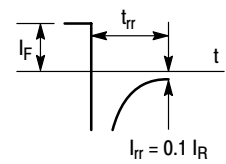
I_F = 10 mA
V_R = 6 V
R_L = 100 Ω

Figure 1. Reverse Recovery Time Equivalent Test Circuit

M1MA151WAT1, M1MA152WAT1
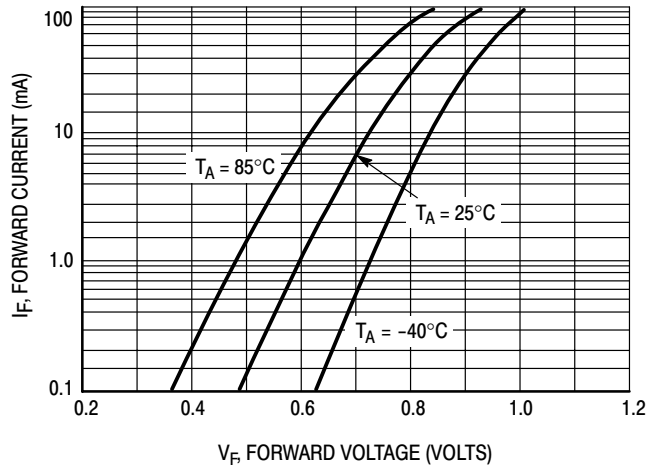
Figure 2. Forward Voltage
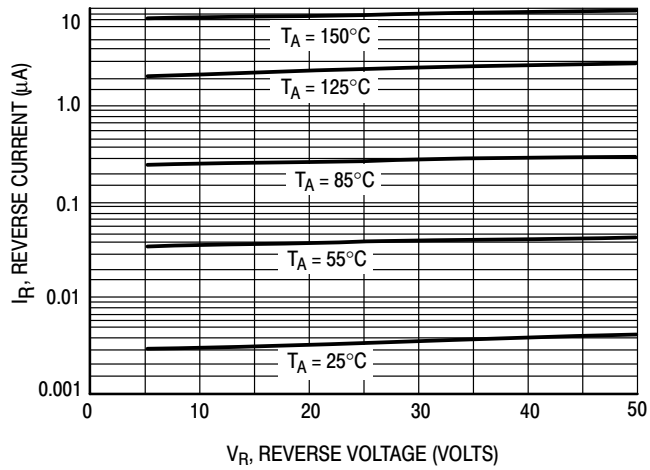
Figure 3. Leakage Current
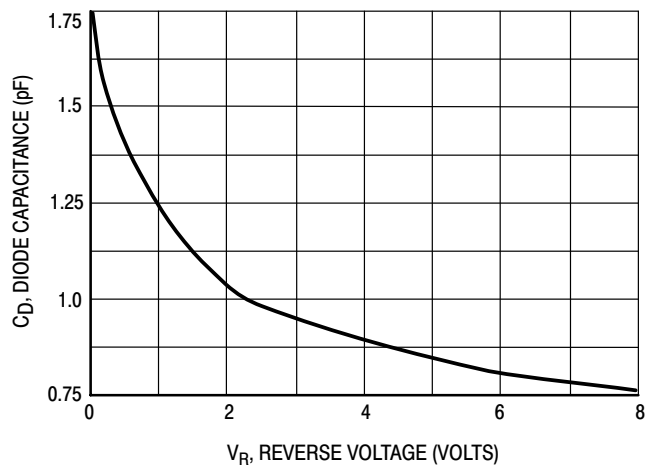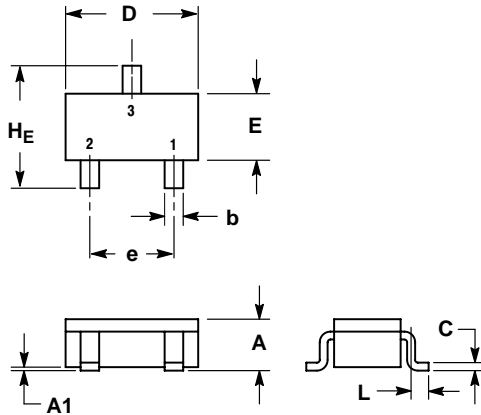

Figure 4. Capacitance

PACKAGE DIMENSIONS

**SC−59**
CASE 318D−04
ISSUE G

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
c	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
H_E	2.50	2.80	3.00	0.099	0.110	0.118

SOLDERING FOOTPRINT*

SCALE 10:1 $\left(\dfrac{mm}{inches}\right)$
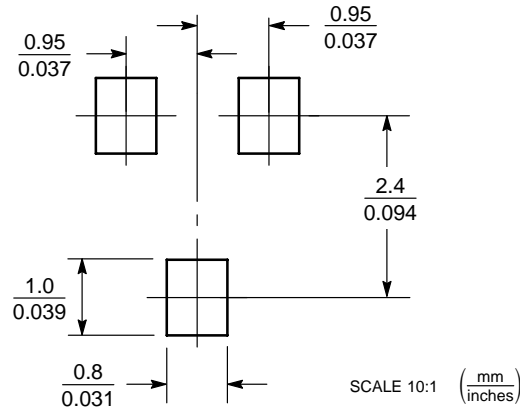
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.